# 1.5V Drive Nch MOSFET

RQ6C050UN Data Sheet

#### Structure

Silicon N-channel MOSFET

## Features

- 1) Low On-resistance.
- 2) Space saving, small surface mount package (TSMT6).
- 3) 1.5V drive

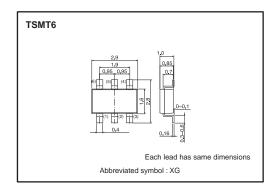
## Applications

Switching

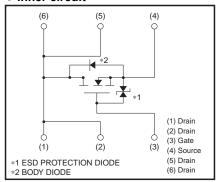
Packaging specifications

Туре	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
	Marking	FD

#### Dimensions



## Inner circuit



• Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit	
Drain-source voltage		VDSS	20	V	
Gate-source voltage		V <sub>GSS</sub>	±10	V	
Dunin summent	Continuous	I <sub>D</sub>	±5.0	Α	
Drain current	Pulsed	IDP *1	±10	Α	
Source current	Continuous	Is	1.0	А	
(Body diode)	Pulsed	I <sub>SP</sub> *1	10	А	
Total power dissipation		Pp *2	1.25	W	
Channel temperature		Tch	150	°C	
Range of storage temperature		Tstg	-55 to +150	°C	

<sup>∗1</sup> Pw≤10μs, Duty cycle≤1%

### • Thermal resistance

- 1110111111111100			
Parameter	Symbol	Limits	Unit
Channel to ambient	Rth(ch-a)*	100	°C/W

<sup>\*</sup> Mounted on a ceramic board

<sup>\*2</sup> Mounted on a ceramic board

Data Sheet

## • Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	Igss	_	-	±10	μΑ	Vgs=±10V, V ps=0V
Drain-source breakdown voltage	$V_{(BR)\;DSS}$	20	-	_	V	I <sub>D</sub> = 1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	1	μΑ	V <sub>DS</sub> = 20V, V <sub>GS</sub> =0V
Gate threshold voltage	VGS (th)	0.3	ı	1.0	V	VDS= 10V, ID= 1mA
	R <sub>DS (on)</sub> *	-	22	30	mΩ	I <sub>D</sub> = 5.0A, V <sub>GS</sub> = 4.5V
Static drain-source on-state		_	27	38	mΩ	I <sub>D</sub> = 5.0A, V <sub>GS</sub> = 2.5V
resistance		_	32	45	mΩ	I <sub>D</sub> = 2.5A, V <sub>GS</sub> = 1.8V
		_	40	80	mΩ	I <sub>D</sub> = 1.0A, V <sub>GS</sub> = 1.5V
Forward transfer admittance	Yfs *	6.5	_	_	S	V <sub>DS</sub> = 10V, I <sub>D</sub> = 5.0A
Input capacitance	Ciss	_	900	_	pF	V <sub>DS</sub> = 10V
Output capacitance	Coss	_	190	_	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	Crss	_	120	_	pF	f=1MHz
Turn-on delay time	t <sub>d (on)</sub> *	_	15	_	ns	V <sub>DD</sub> ≒ 10V
Rise time	tr *	_	25	_	ns	ID= 2.5A
Turn-off delay time	t <sub>d (off)</sub> *	_	70	_	ns	$V_{GS} = 4.5V$ $R_L = 4\Omega$
Fall time	t <sub>f</sub> *	_	100	_	ns	R <sub>G</sub> =10Ω
Total gate charge	Qg *	_	12	_	nC	V <sub>DD</sub> = 10V, I <sub>D</sub> = 5.0A
Gate-source charge	Q <sub>gs</sub> *	_	2.5	_	nC	V <sub>GS</sub> = 4.5V
Gate-drain charge	Q <sub>gd</sub> *	_	1.7	_	nC	$RL = 2\Omega$ , $Rg=10\Omega$

<sup>\*</sup>Pulsed

## ● Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	Vsp *	_	_	1.2	V	I <sub>S</sub> = 1.0A, V <sub>GS</sub> =0V

<sup>\*</sup>Pulsed

#### Electrical characteristics curves

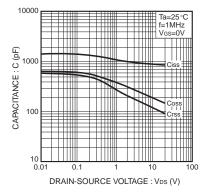


Fig.1 Typical Capacitance vs. Drain-Source Voltage

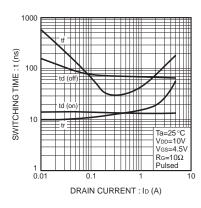


Fig.2 Switching Characteristics

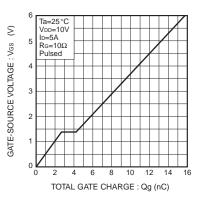


Fig.3 Dynamic Input Characteristics

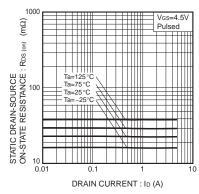


Fig.7 Static Drain-Source On-State Resistance vs. Drain current (I)

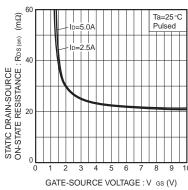


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

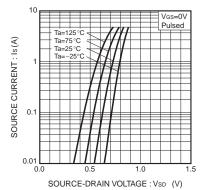


Fig.6 Source Current vs. Source-Drain Voltage

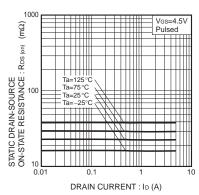


Fig.7 Static Drain-Source On-State Resistance vs. Drain current (I)

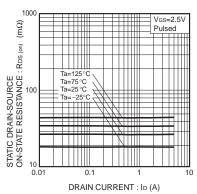


Fig.8 Static Drain-Source On-State Resistance vs. Drain current (II)

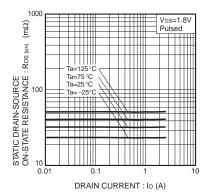


Fig.9 Static Drain-Source On-State Resistance vs. Drain current (III)

2014.05 - Rev.A

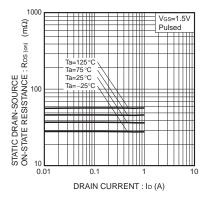


Fig.10 Static Drain-Source On-State Resistance vs. Drain current (IV)

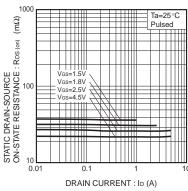


Fig.11 Static Drain-Source On-State Resistance vs. Drain current (V)

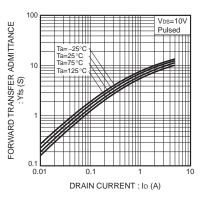


Fig.12 Forward Transfer Admittance vs. Drain current

## • Measurement circuit

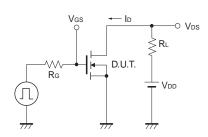


Fig.13 Switching Time Measurement Circuit

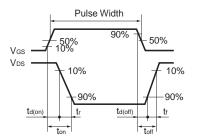


Fig.14 Switching Waveforms

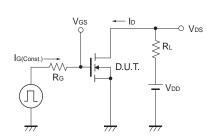


Fig.15 Gate Charge Measurement Circuit

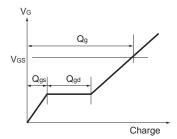


Fig.16 Gate Charge Waveform

## Notes

- 1) The information contained herein is subject to change without notice.
- Before you use our Products, please contact our sales representative and verify the latest specifications:
- 3) Although ROHM is continuously working to improve product reliability and quality, semiconductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Poducts beyond the rating specified by ROHM
- 4) Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.
- 5) The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use of such technical information.
- 6) The Products are intended for use in general electronic equipment (i.e. AV/OA devices, communication, consumer systems, gaming/entertainment sets) as well as the applications indicated in this document.
- 7) The Products specified in this document are not designed to be radiation tolerant.
- 8) For use of our Products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a ROHM representative: transportation equipment (i.e. cars, ships, trains), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems.
- Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters.
- 10) ROHM shall have no responsibility for any damages or injury arising from non-compliance with the recommended usage conditions and specifications contained herein.
- 11) ROHM has used reasonable care to ensur the accuracy of the information contained in this document. However, ROHM does not warrants that such information is error-free, and ROHM shall have no responsibility for any damages arising from any inaccuracy or misprint of such information.
- 12) Please use the Products in accordance with any applicable environmental laws and regulations, such as the RoHS Directive. For more details, including RoHS compatibility, please contact a ROHM sales office. ROHM shall have no responsibility for any damages or losses resulting non-compliance with any applicable laws or regulations.
- 13) When providing our Products and technologies contained in this document to other countries, you must abide by the procedures and provisions stipulated in all applicable export laws and regulations, including without limitation the US Export Administration Regulations and the Foreign Exchange and Foreign Trade Act.
- 14) This document, in part or in whole, may not be reprinted or reproduced without prior consent of ROHM



Thank you for your accessing to ROHM product informations. More detail product informations and catalogs are available, please contact us.

## ROHM Customer Support System

http://www.rohm.com/contact/